To:

Mail Stop Appeal Brief - Patents

Technology Center 2800

Facsimile Number: 571-273-8300

From:

Charles A. Brill

Texas Instruments Incorporated Facsimile: 972-917-4418

Phone: 972-917-4379

Total Pages Sent 17

RECEIVED CENTRAL FAX CENTER

NOV 0 2 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Brenner

Art Unit: 2814

Serial No.: 10/038,813

Examiner: Trinh, Hoa B.

Filed: 31 December 2001

Docket No. TI-30637

For: SEPARATING WAFERS COATED WITH PLASTIC FILMS

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below:

calas

November 2, 2005

Charles A. Brill

Date

FACSIMILE COVER SHEET

X FACSIMILE COVER SHEET NEW APPLICATION DECLARATION (# Pages) ASSIGNMENT (# Pages) FORMAL DRAWINGS INFORMAL DRAWINGS CONTINUATION APP'N (# Pages) DIVISIONAL APP'N		AMENDMENT (# Pages) EOT (1 Month) NOTICE OF APPEAL X AMENDED APPEAL BRIEF (15 Pages) REPLY BRIEF (# Pages) PETITION ISSUE FEE (# Pages) X APPEAL TRANSMITTAL	
NAME OF INVENTOR(S):		RECEIPT DATE & SERIAL NO.:	
Brenner		Application No.: 10/038,813	
TITLE OF INVENTION:		Filing Date: 12/31/2001	
SEPARATING WAFERS COATED WITH			
PLASTIC FILMS			
TI FILE NO.:	DEPOSIT ACCT. NO.:		
TI-30637	20-0668	<u>.</u>	
FAXED: 11/02/2005			
DUE: 11/04/2005			
ATTY/SEC'Y: CAB:ss		1	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not walved by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated PO Box 655474, M/S 3999 Dallas, TX 75265

NOV 0 2 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Brenner Serial No.: 10/038,813

Examiner: Trinh, Hoa B. Docket No.: TI-30637

Filed: 31 December 2001

SEPARATING WAFERS COATED WITH PLASTIC FILMS

APPEAL BRIEF TRANSMITTAL

2 November 2005

Mail Stop Appeal Brief-Patents Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450 MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8 (a)

hereby certify that the above correspondence is being deposited with the U.S. Posta Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria. Virginia, 22313-1450, or facsimile transmitted to the U.S. Patent and Trademark Office, on the date shown below.

ZKbu 2005

Art Unit: 2814

Sir:

Transmitted herewith is an Amended Appeal Brief in the above-identified application. The Amended Appeal Brief is filed in response to the Notification of Non-Compliant Appeal Brief mailed 4 October 2005, and includes an Evidence Appendix and a Related Proceedings Appendix.

As the \$500.00 fee for filing an Appeal Brief has already been paid, it is believed no additional fees are due as a result of this communication. Nevertheless, please charge any necessary fees, including any extension of time fees, or credit overpayment to the deposit accout of Texas Instruments Incorporated, Deposit Account No. 20-0668.

Respectfully submitted,

(11103:11

Charles A. Brill

Attorney for Applicant(s)

Reg. No. 37,786

Texas Instruments Incorporated P. O. Box 655474, MS 3999 Dallas, Texas 75265

Telephone: (972) 917-4379

Fax: (972) 917-4418

11/03/2005 TL0111 00000019 200668

10038813

01 FC:1402

500.00 DA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Brenner

Art Unit: 2814

RECEIVED

Serial No.: 10/038,813

Filed: 31 December 2001

CENTRAL FAX CENTER Examiner: Trinh, Hoa B.

NOV 0 2 2005

Docket No.: TI-30637

SEPARATING WAFERS COATED WITH PLASTIC FILMS

AMENDED APPEAL BRIEF UNDER 37 C.F.R. § 41.37

2 November 2005

Mails Stop Appeal Brief - Patents Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents P.O. Box 1450, Alexandria, Virginia 22313-1450, or facsimile transmitted to the U.S. Patent and Trademark Office, on the date shown below.

Dear Sir.

The following Amended Appeal Brief is respectfully submitted in connection with the above-identified application in response to the Notification of Non-Compliant Appeal Brief mailed 4 October 2005, the Final Rejection mailed 7 January 2005, and the Advisory Action mailed 2 May 2005. Please charge all required fees, including any extension of time fees, to the deposit account of Texas Instruments Incorporated, Deposit Account No. 20-0668.

REAL PARTY IN INTEREST

The real party in interest is Texas Instruments Incorporated, to whom this application is assigned.

TI-30637 Appeal Brief - Page 1 of 15

RELATED APPEALS AND INTERFERENCES

There are no related appeals or interferences known to the Applicant's legal representative.

STATUS OF THE CLAIMS

This application was filed on 31 December 2001 with twenty three claims, one of which was written in independent form. No claims have been amended or added. All claims, Claims 1-23, have been rejected and are under appeal.

STATUS OF THE AMENDMENTS

A response to the final rejection was submitted on 14 April 2005. The response after final rejection did not amend any claims, and the Examiner indicated it would be entered for purposes of appeal.

SUMMARY OF CLAIMED SUBJECT MATTER

The present invention provides a useful process that enables devices, such as micromirror arrays and other micro-electro-mechanical systems, to be tested prior to wafer separation and packaging. In the case of micromirror arrays, the package and optical window are very expensive. Therefore, the ability to test the micromirror arrays in wafer form and package only the known good die is extremely important. To enable the device to be tested, the sacrificial layers supporting the mirror array during fabrication are removed. The mirrors are then prone to damage from debris or other contact and must be protected during the wafer separation and packaging steps.

The micromechanical device is protected during the wafer separation process by a protective layer. The protective layer is difficult to establish and remove without damage to the fragile micromechanical components. The protective overcoat is described on page

TI-30637 Appeal Brief - Page 2 of 15

9 of the specification. In general, the materials that are suitable for protective overcoat layers are easily sawn when the wafer is sawn. Unfortunately, as described in lines 4-12 of page 10, the overcoat layers tend to be slightly plastic. This leads to deformation and delamination during the saw process and damage to the underlying micromechanical elements. The present invention teaches the use of a brittle layer over the protective layer to prevent damage from the deformation and delamination of the protective layer. The combination of a protective layer and a brittle layer allows the use of a protective layer that is selected for its ability to both encapsulate the micromechanical devices and be removed without damage to the devices. The brittle layer material may then be selected for its ability to prevent deformation and delamination damage without regard for its ability to be applied to an unprotected device.

GROUNDS OF REJECTION TO BE REVIEWED ON APPEAL

1. Whether Claims 1-14 and 20-22 are anticipated under 35 U.S.C. § 102 (e) by U.S. Patent No. 6.335.224 B1 to Peterson et al. ("Peterson").